

**Amendments to the Claims**

1. *(Previously Presented)* A method of wedge-bonding wires in the manufacture of electronic devices, wherein:

a reversible bonding tool is used having a wedge-bonding tip at opposite ends of the tool,

and, after using the wedge-bonding tip at one end for bonding wires, the tool is reversed to use the wedge-bonding tip at the opposite end for bonding further wires.

2. *(Original)* A method according to Claim 1, wherein the bonding tool comprises a shank of tungsten carbide having the wedge-bonding tips at opposite ends of the shank.

3. *(Previously Presented)* A method according to Claim 1, wherein the wires comprise aluminum or gold and are ultra-sonically bonded using a transducer coupled to the tool.

Claims 4-12 *(Cancelled)*